

**Supporting Information for:**

**Promoting 2D growth in transition metal sulfide semiconductor nanostructures via halide ions**

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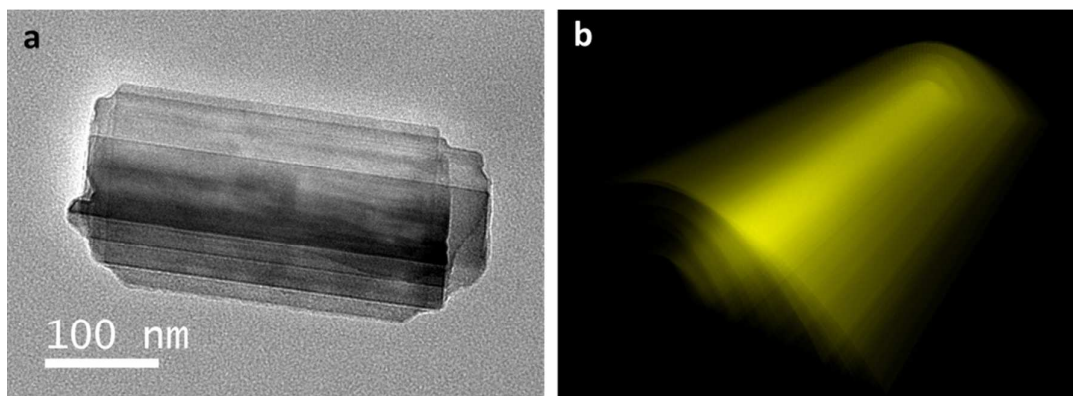
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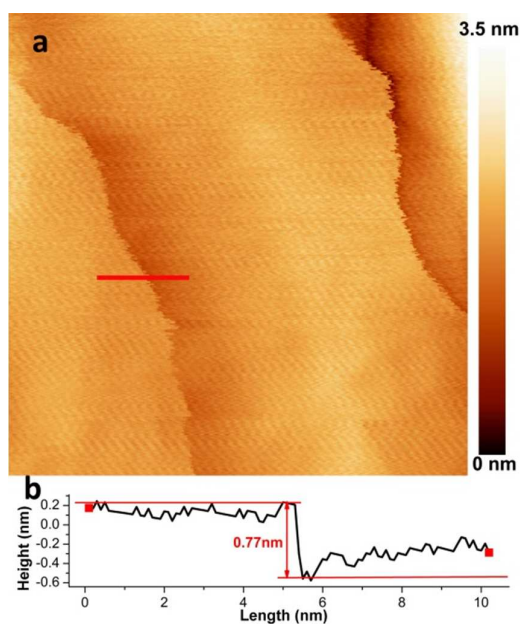
Homepage: <http://staff.science.nus.edu.sg/~chmchany/Home.html>

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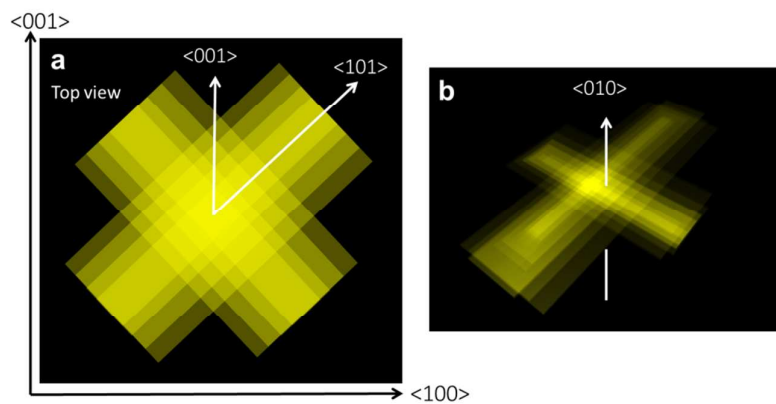
## I Additional characterization data:



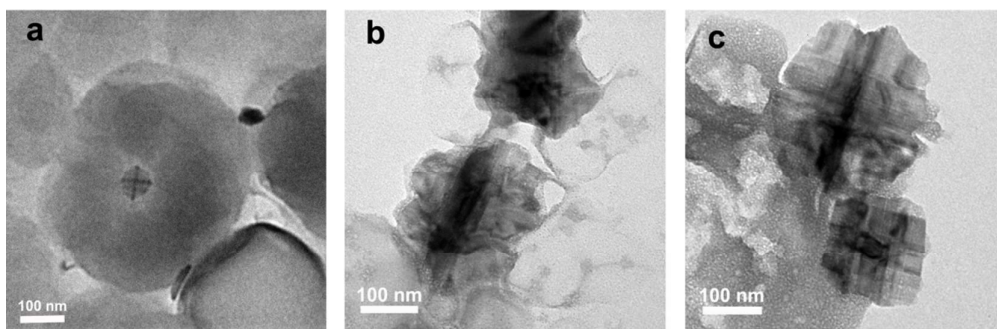
**Figure S1.** (a) TEM image of multiple sheet-like  $\text{Ni}_9\text{S}_8$  stacked in parallel. (b) Schematic illustration of  $\text{Ni}_9\text{S}_8$  sheets within a stack. When incomplete growth of the four wings occurs,  $\text{Ni}_9\text{S}_8$  nanoplates have a more belt-like morphology and can form a stack comprising of multiple nanosheets.



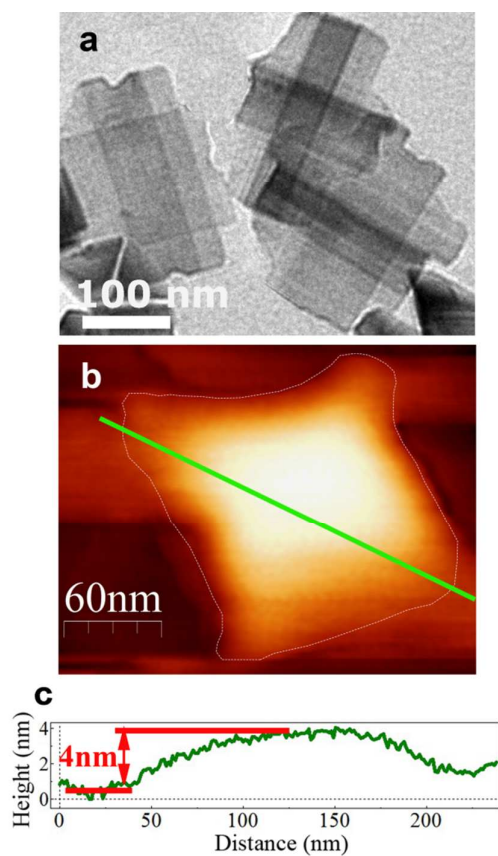
**Figure S2.** (a) AFM image which shows a series of step-edges on the synthesized  $\text{Ni}_9\text{S}_8$  nanoplates. (b) Height profile across a typical step-edge, which shows that the average thickness of each step is around  $\sim 0.8$  nm.



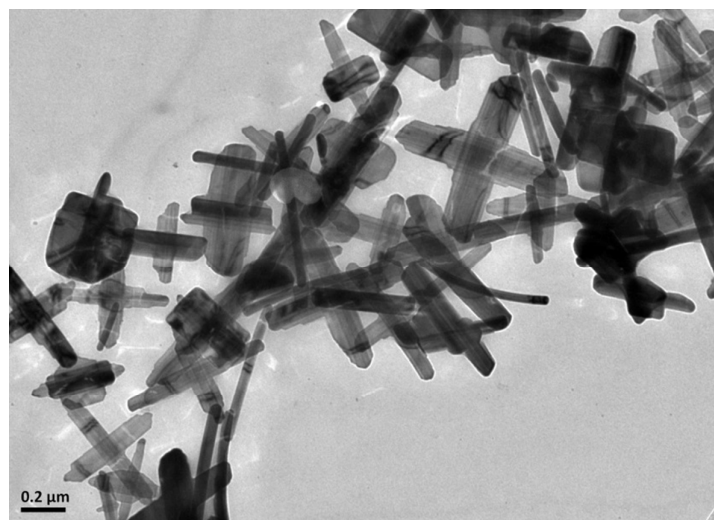
**Figure S3.** Schematic illustration of growth axes of a cross  $\text{Ni}_9\text{S}_8$  nanoplate from (a) top-view and (b)  $45^\circ$  angled side view respectively.



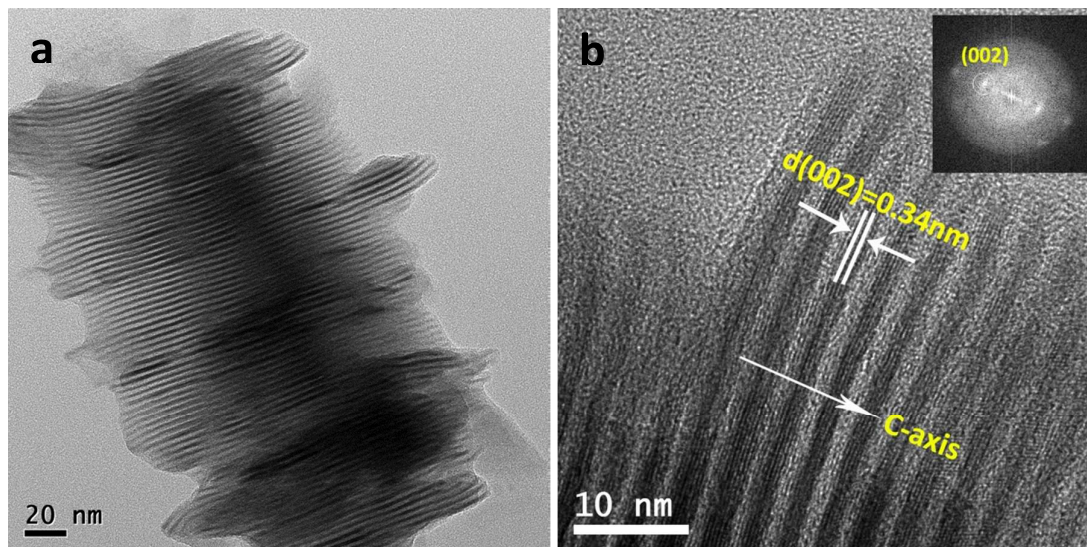
**Figure S4.** Growth evolution of  $\text{Ni}_9\text{S}_8$  nanocrystals from (a)  $230^\circ\text{C}$ , (b)  $250^\circ\text{C}$ , (c) maintained at  $250^\circ\text{C}$  for 5 min.



**Figure S5.** Ni<sub>9</sub>S<sub>8</sub> nanoplates obtained at lower Ni(II) precursor concentration. (a) TEM image of the Ni<sub>9</sub>S<sub>8</sub> sheet; (b) AFM image of a single Ni<sub>9</sub>S<sub>8</sub> sheet; (c) Height profile across the green line in (b) showing that the height is around 4 nm. Given the ligands at the basal planes, the thickness of the sheet is therefore less than 4 nm.

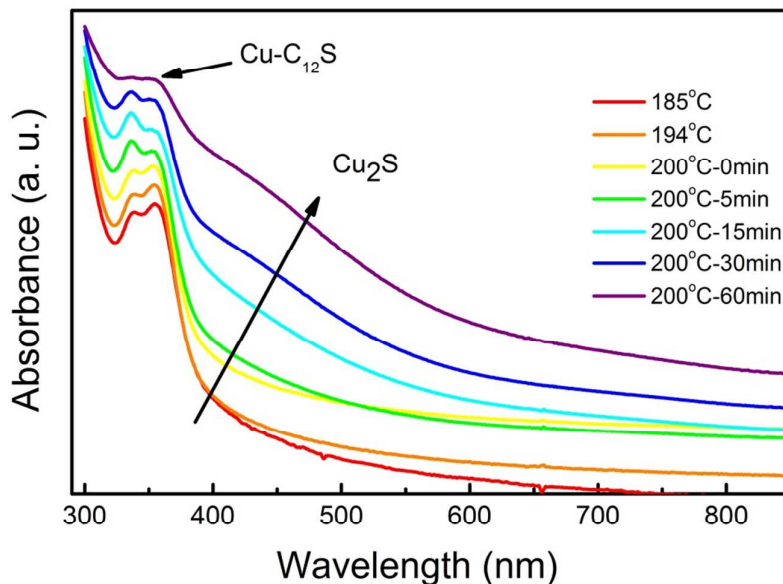


**Figure S6.** Low resolution TEM image of  $\text{Ni}_9\text{S}_8$  nanostructures obtained using  $\text{NiBr}_2$  as the precursor, where all the other parameters were kept the same as that of the synthesis with  $\text{Cl}^-$ , with the sole exception that the growth temperature was set at 265 - 270 °C. The resulting nanocrystals were several times larger in dimensions and with a poorer size distribution compared with those using  $\text{Cl}^-$ , but clearly exhibited a cross-like plate morphology.

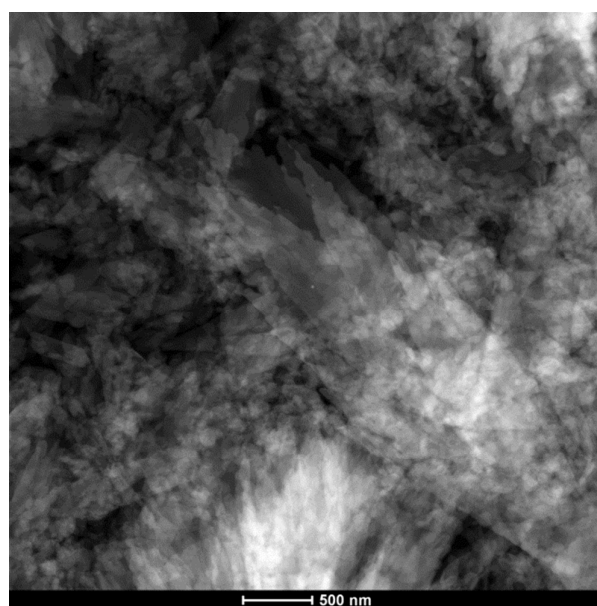


**Figure S7.** a) TEM image of stacks of ultrathin  $\text{Cu}_2\text{S}$  nanoplates, where the average thickness of these sheets are below 2 nm; b) Corresponding HRTEM image of the same sample, showing a lattice d-spacing of 0.34 nm which represents the (0 0 2) plane. Inset shows the FFT of the selected area where the (0 0 2) plane spot in the pattern is clearly evident.

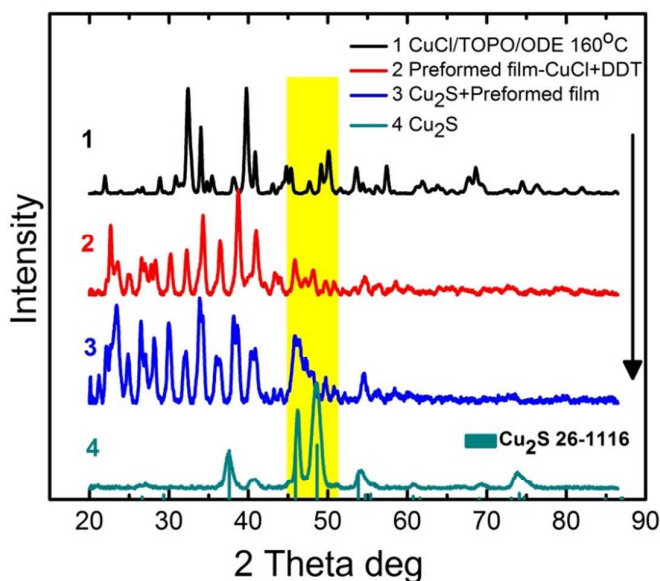




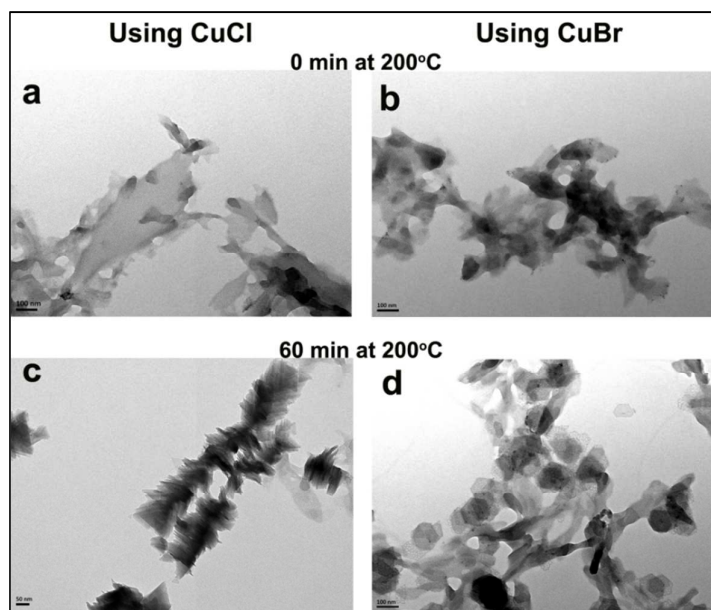
**Figure S8.** UV-Vis spectra of the aliquots taken from reaction pot during the Cu<sub>2</sub>S growth. The absorbance peaks at the lower wavelength range of 330-360 nm is attributed to the Cu-dodecanethiolate bond. These 2 peaks are gradually decreasing due to the breakdown of dodecanethiolate during the growth of the Cu<sub>2</sub>S nanocrystal. As the reaction proceeds, the Cu<sub>2</sub>S absorbance band (400 ~550 nm) starts to emerge and becomes more prominent as the Cu thiolate peak decreases.



**Figure S9.** HAADF-STEM image of a preformed film comprising of Cu, S and Cl. Consumption of the film eventually leads to the nucleation and growth of Cu<sub>2</sub>S nanoplates.



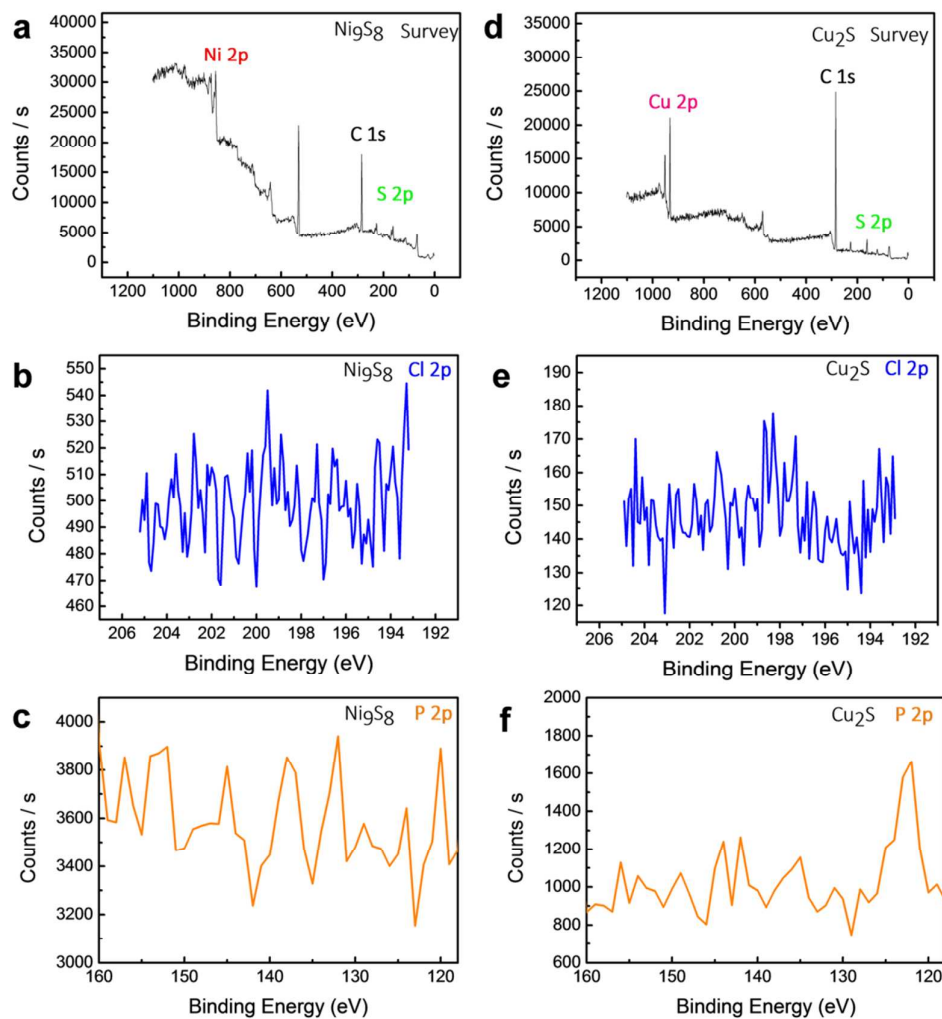
**Figure S10.** The evolution of XRD from (1)  $\text{CuCl} \cdot \text{H}_2\text{O}$  (2) the preformed film after DDT injection to the pot, when the growth temperature was at  $200^\circ\text{C}$ , (3) the  $\text{Cu}_2\text{S}$  nanoplates in co-existence with the preformed film of Cu thiolate, to (4) the final  $\text{Cu}_2\text{S}$  nanoplates. (All samples were prepared in powder form).



**Figure S11.** TEM images of experiments comparing the rate of consumption of the preformed film while using (a,c)  $\text{CuCl}$  and (b,d)  $\text{CuBr}$  as the Cu precursor respectively. When the reaction temperature reached  $200^\circ\text{C}$ , both aliquots showed a similar looking preformed film structure, however after growth at (c)  $200^\circ\text{C}$  for 60 min, the preformed films were almost fully consumed, leaving a large number of  $\text{Cu}_2\text{S}$  nanoplates; on the other hand, the consumption of the preformed film in the case of  $\text{CuBr}$  was very slow, and it is seen in (d) that a significant fraction of the preformed film remained even after 60 min of growth. Nevertheless, it is seen that hexagonal-shaped  $\text{Cu}_2\text{S}$  nanosplates were produced.

**Table S1.** Elemental analysis on preformed film.

Cu	Cu(w%)	S(w%)	Cl(w%)	Br(w%)	Cu:S:Halide(mol)
Preformed film(Cl)	18.86%	11.27%	1.30%		1 : 0.83 : 0.11
Preformed film(Br)	23.79%	9.86%		1.43%	1 : 1.2 : 0.12
Ni	Ni(w%)	S(w%)	Cl(w%)		Ni:S:Halide(mol)
Preformed film(Cl)	24.17%	1.87%	27.17%		1 : 0.14 : 1.8



**Figure S12.** XPS of (a) Ni<sub>9</sub>S<sub>8</sub>, (d) Cu<sub>2</sub>S nanoplates, where Cl 2p signal window is further elaborated in (b) and (e) respectively, (c) and (f) is the signal of P 2p. We did not get any observable Cl and P signal from both of our final nanoplates.